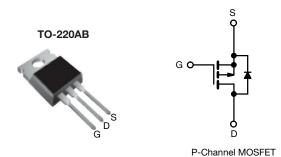


## **Power MOSFET**



PRODUCT SUMMA	RY	
V <sub>DS</sub> (V)	-1	00
$R_{DS(on)}(\Omega)$	V <sub>GS</sub> = -10 V	1.2
Q <sub>g</sub> max. (nC)	8	.7
Q <sub>gs</sub> (nC)	2	.2
Q <sub>gd</sub> (nC)	4	.1
Configuration	Sin	gle

#### **FEATURES**

- Dynamic dV/dt rating
- Repetitive avalanche rated
- P-channel
- 175 °C operating temperature
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### Note

\* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

### **DESCRIPTION**

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF9510PbF
Lead (Pb)-free and halogen-free	IRF9510PbF-BE3

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub>	= 25 °C, unle	ess otherwis	e noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage		$V_{DS}$	-100	V		
Gate-source voltage		$V_{GS}$	± 20	7 v		
Continuous drain current	\/ at 10 \/	T <sub>C</sub> = 25 °C	,	-4.0		
Continuous drain current	$V_{GS}$ at 10 V $T_C = 100 ^{\circ}\text{C}$ $I_D$		-2.8	Α		
Pulsed drain current a			I <sub>DM</sub>	-16		
Linear derating factor				0.29	W/°C	
Single pulse avalanche energy <sup>b</sup>	· ·		mJ			
Repetitive avalanche current a			I <sub>AR</sub>	-4.0	Α	
Repetitive avalanche energy <sup>a</sup>			E <sub>AR</sub>	4.3	mJ	
Maximum power dissipation	$T_C = 1$	25 °C	P <sub>D</sub>	43	W	
Peak diode recovery dV/dt <sup>c</sup>	$T_{C} = 25 ^{\circ} \text{C}$ $P_{D}$ 43 W dV/dt -5.5 V/ns		V/ns			
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	00	
Soldering recommendations (peak temperature) <sup>d</sup>	For	10 s		300	°C	
	6.22.04.1	0.00 140		10	lbf ⋅ in	
Mounting torque	6-32 or M3 screw 1.1	N⋅m				

### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b.  $V_{DD}$  = -25 V, starting  $T_J$  = 25 °C, L = 18 mH,  $R_q$  = 25  $\Omega$ ,  $I_{AS}$  = -4.0 A (see fig. 12)
- c.  $I_{SD} \le -4.0$  A,  $dI/dt \le 75$  A/ $\mu$ s,  $V_{DD} \le V_{DS}$ ,  $T_J \le 175$  °C
- d. 1.6 mm from case



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# Vishay Siliconix

THERMAL RESISTANCE RAT	INGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R <sub>thJA</sub>	-	62	
Case-to-sink, flat, greased surface	R <sub>thCS</sub>	0.50	-	°C/W
Maximum junction-to-case (drain)	R <sub>thJC</sub>	-	3.5	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0$	) V, I <sub>D</sub> = -250 μA	-100	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I <sub>D</sub> = -1 mA	-	- 0.091	-	V/°C
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = \	/ <sub>GS</sub> , I <sub>D</sub> = -250 μA	-2.0	-	-4.0	V
Gate-source leakage	I <sub>GSS</sub>	V	<sub>GS</sub> = ± 20 V	-	-	± 100	nA
Zero gate voltage drain current	I <sub>DSS</sub>		100 V, V <sub>GS</sub> = 0 V	-	-	-100	μΑ
Drain-source on-state resistance	R		$V_{GS} = 0 \text{ V}, T_{J} = 150 \text{ °C}$ $I_{D} = -2.4 \text{ A}^{b}$		-	-500 1.2	Ω
Forward transconductance	R <sub>DS(on)</sub>		50 V, I <sub>D</sub> = -2.4 A <sup>b</sup>	1.0	<u> </u>	-	S
Dynamic Dynamic	9 <sub>fs</sub>	v <sub>DS</sub> = -:	50 V, I <sub>D</sub> = -2.4 A ~	1.0		_	0
Input capacitance					200	l _	Т
Output capacitance	Ciss	$V_{GS} = 0 \text{ V}, \\ V_{DS} = -25 \text{ V}, \\ f = 1.0 \text{ MHz, see fig. 5}$			94		pF
Reverse transfer capacitance	C <sub>oss</sub>				18	-	
Total gate charge	Q <sub>g</sub>	+	T C	_	-	8.7	
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = -10 V	$I_D = -4.0 \text{ A}, V_{DS} = -80 \text{ V},$	_		2.2	nC
Gate-drain charge	$Q_{gd}$	VGS = 10 V	see fig. 6 and 13 b		_	4.1	
Turn-on delay time	t <sub>d(on)</sub>	1		_	10	-	
Rise time	t <sub>r</sub>	$V_{DD} = -50 \text{ V}, I_D = -4.0 \text{ A},$ $R_g = 24 \ \Omega, R_D = 11 \ \Omega, \text{ see fig. } 10^\text{ b}$			27	_	ns
Turn-off delay time	t <sub>d(off)</sub>			_	15	_	
Fall time	t <sub>f</sub>			_	17	_	
Gate input resistance	R <sub>q</sub>	f = 1 MHz, open drain		1.5	_	7.9	Ω
Internal drain inductance	L <sub>D</sub>	Between le 6 mm (0.25")	Between lead, 6 mm (0.25") from		4.5	-	<u> </u>
Internal source inductance	Ls	package and center of die contact		-	7.5	-	nH
Drain-Source Body Diode Characteristic	es			•	•		
Continuous source-drain diode current	I <sub>S</sub>	,	MOSFET symbol showing the		-	-4.0	^
Pulsed diode forward current <sup>a</sup>	I <sub>SM</sub>	integral reverse p - n junction diode		-	-	-16	A
Body diode voltage	$V_{SD}$	T <sub>J</sub> = 25 °C, I <sub>S</sub> = -4.0 A, V <sub>GS</sub> = 0 V b		-	-	-5.5	V
Body diode reverse recovery time	t <sub>rr</sub>	$T_J = 25 \text{ °C}, I_F = -4.0 \text{ A}, dI/dt = 100 \text{ A/}\mu\text{s}^b$		-	82	160	ns
Body diode reverse recovery charge	Q <sub>rr</sub>			-	0.15	0.30	μC
Forward turn-on time	t <sub>on</sub>	Intrinsic turi	n-on time is negligible (turi	n-on is do	minated b	v Le and	L <sub>D</sub> )

## Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width  $\leq 300~\mu s;$  duty cycle  $\leq 2~\%$



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

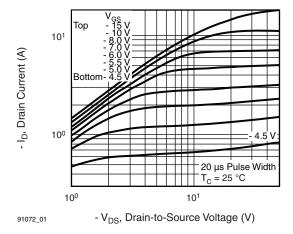


Fig. 1 - Typical Output Characteristics, TC = 25 °C

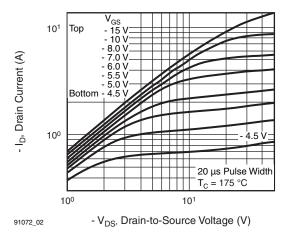


Fig. 2 - Typical Output Characteristics, TC = 175 °C

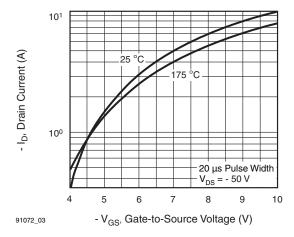


Fig. 3 - Typical Transfer Characteristics

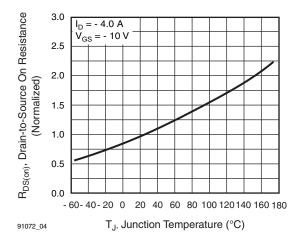


Fig. 4 - Normalized On-Resistance vs. Temperature

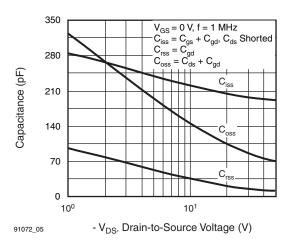


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

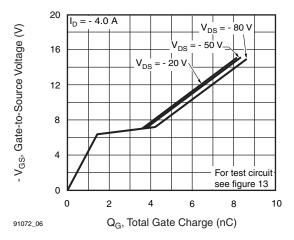


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



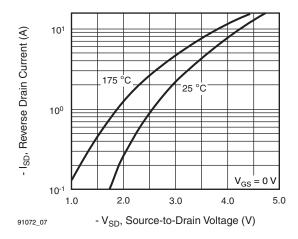


Fig. 7 - Typical Source-Drain Diode Forward Voltage

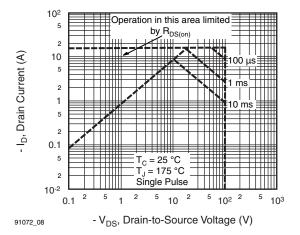


Fig. 8 - Maximum Safe Operating Area

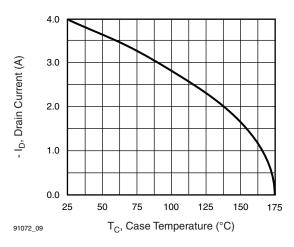


Fig. 9 - Maximum Drain Current vs. Case Temperature

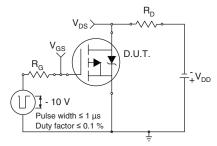


Fig. 10a - Switching Time Test Circuit

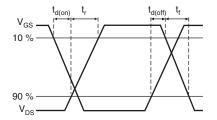


Fig. 10b - Switching Time Waveforms

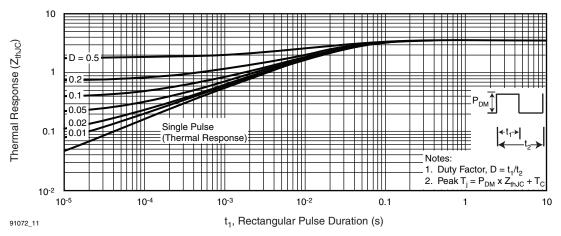


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



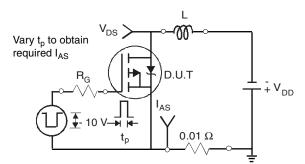


Fig. 12a - Unclamped Inductive Test Circuit

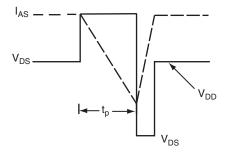


Fig. 12b - Unclamped Inductive Waveforms

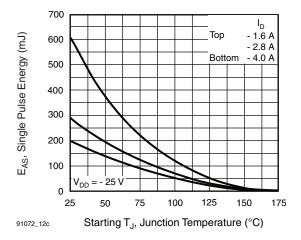


Fig. 12 c- Maximum Avalanche Energy vs. Drain Current

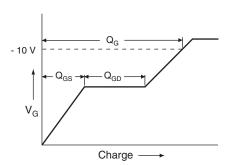


Fig. 13a - Basic Gate Charge Waveform

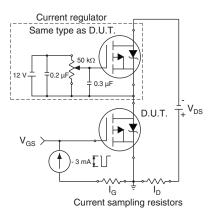
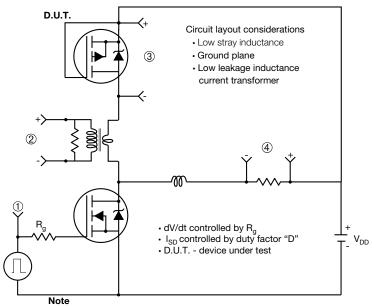


Fig. 13b - Gate Charge Test Circuit



## Peak Diode Recovery dV/dt Test Circuit



• Compliment N-Channel of D.U.T. for driver

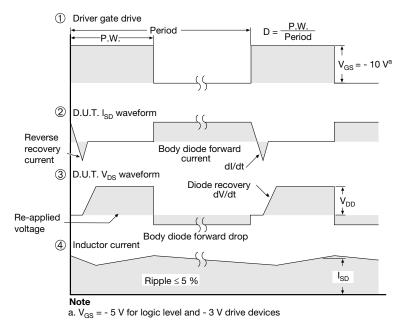


Fig. 14 - For P-Channel

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## TO-220-1



DIM.	MILLIM	IETERS	INC	HES
	MIN.	MAX.	MIN.	MAX.
Α	4.24	4.65	0.167	0.183
b	0.69	1.02	0.027	0.040
b(1)	1.14	1.78	0.045	0.070
С	0.36	0.61	0.014	0.024
D	14.33	15.85	0.564	0.624
Е	9.96	10.52	0.392	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.10	6.71	0.240	0.264
J(1)	2.41	2.92	0.095	0.115
L	13.36	14.40	0.526	0.567
L(1)	3.33	4.04	0.131	0.159
ØΡ	3.53	3.94	0.139	0.155
Q	2.54	3.00	0.100	0.118

### Note

DWG: 6031

•  $M^* = 0.052$  inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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